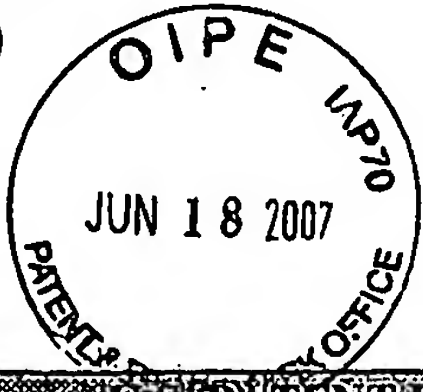



INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 007734 FPS/MMCS/APC		SERIAL NO. 10/665,165	
				APPLICANT Joseph Young J. PAIK			
				FILING DATE September 18, 2003		GROUP	
							
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
<i>SM</i>	4,957,605	09/18/90	Hurwitt et al.			04/17/89	
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	5,369,544	11/29/94	Mastrangelo			04/05/93	
	5,444,837	08/22/95	Bomans et al.			12/29/93	
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<i>SM</i>	6,281,127 B1	08/28/01	Shue			04/15/99	
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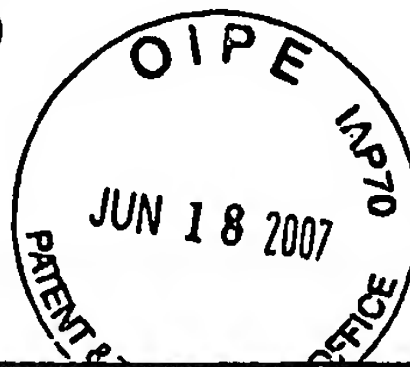
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			APPLICANT Joseph Young J. PAIK			
			FILING DATE September 18, 2003		GROUP	
U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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<i>Am</i>	6,728,587 B2	04/27/04	Goldman et al.			12/27/00
EXAMINER <i>ma A</i>			DATE CONSIDERED <i>1/21/2008</i>			

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				APPLICANT Joseph Young J. PAIK			
				FILING DATE September 18, 2003		GROUP	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
_____	EP 0 932 195 A1	07/28/99	EP			X	
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SERIAL NO.
10/665,165

APPLICANT
Joseph Young J. PAIK

FILING DATE
September 18, 2003

GROUP

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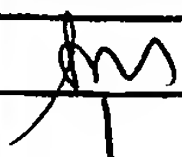
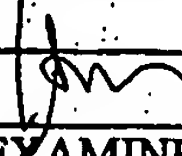
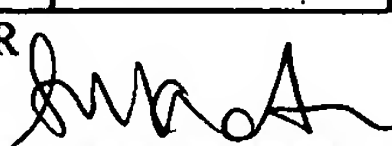
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DATE CONSIDERED

1/21/08

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U.S. PATENT DOCUMENTS							
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	3,229,198	01/11/66	Libby			09/28/62	
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		5,260,868	11/09/93	Gupta et al.			10/15/91
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<i>om</i>	5,270,222	12/14/93	Moslehi			12/31/90	
	5,283,141	02/01/94	Yoon et al.			03/05/92	
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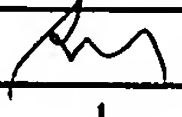


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<i>Am</i>	5,740,429	04/14/98	Wang et al.			07/07/95	
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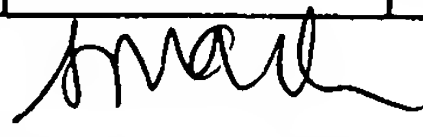
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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	5,828,778	10/27/98	Hagi et al.			07/12/96	
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	5,862,054	01/19/99	Li			02/20/97	
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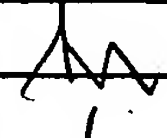
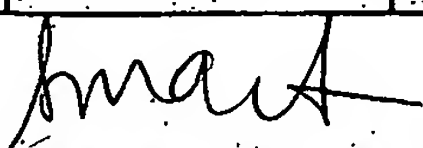
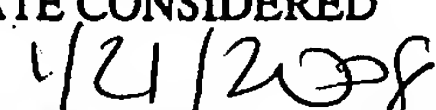
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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)			ATTY. DOCKET NO. 007734 FPS/MMCS/APC		SERIAL NO. 10/665,165	
			APPLICANT Joseph Young J. PAIK			
			FILING DATE September 18, 2003		GROUP	
U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,912,678	06/15/99	Saxena et al.			04/14/97
	5,916,016	06/29/99	Bothra			10/23/97
	5,923,553	07/13/99	Yi			10/05/96
	5,926,690	07/20/99	Toprac et al.			05/28/97
	5,930,138	07/27/99	Lin et al.			09/10/97
	5,940,300	08/17/99	Ozaki			05/08/97
	5,943,237	08/24/99	Van Boxem			10/17/97
	5,960,185	09/28/99	Nguyen			06/24/96
	5,960,214	09/28/99	Sharpe, Jr. et al.			12/04/96
	5,961,369	10/05/99	Bartels et al.			06/04/98
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	6,002,989	12/14/99	Shiba et al.			04/01/97
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	6,054,379	04/25/00	Yau et al.			02/11/98
	6,064,759	05/16/00	Buckley et al.			11/06/97
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	6,077,412	06/20/00	Ting et al.			10/30/98
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	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
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	6,108,092	08/22/00	Sandhu			06/08/99
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U.S. PATENT DOCUMENTS						
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	6,136,163	10/24/00	Cheung et al.			03/05/99
	6,141,660	10/31/00	Bach et al.			07/16/98
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
Am	2001/0040997 A1	11/15/01	Tsap et al.			05/15/01
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EXAMINER <i>maale</i>			DATE CONSIDERED 1/21/2008			

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
/m	2002/0070126 A1	06/13/02	Sato et al.			09/19/01
	2002/0077031 A1	06/20/02	Johannson et al.			07/06/01
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/m	2002/0199082 A1	12/26/02	Shanmugasundram et al.			06/18/02
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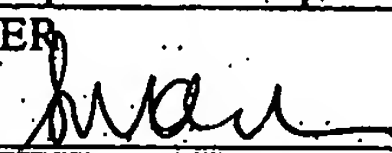
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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
<i>Am</i>	6,503,839 B2	01/07/03	Gonzales et al.			07/03/01	
	2003/0020909 A1	01/30/03	Adams et al.			04/09/01	
	2003/0020928 A1	01/30/03	Ritzdorf et al.			07/09/01	
	6,517,413 B1	02/11/03	Hu et al.			10/25/00	
	6,540,591 B1	04/01/03	Pasady et al.			04/18/01	
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	6,563,308 B2	05/13/03	Nagano et al.			03/27/01	
	6,567,717 B2	05/20/03	Krivokapic et al.			01/19/00	
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	6,590,179 B2	07/08/03	Tanaka et al.			02/26/01	
	6,604,012 B1	08/05/03	Cho et al.			08/23/00	
	6,618,692 B2	09/09/03	Takahashi et al.			02/26/01	
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<i>Am</i>	6,640,151 B1	10/28/03	Somekh et al.			12/22/99	
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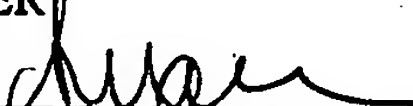
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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
	09/363,966	07/29/99	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
	09/725,908	11/30/00	Chi et al.	Dynamic Subject Information Generation in Message Services of Distributed Object Systems			
	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide			
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow			
	09/927,444	08/13/01	Ward et al.	Dynamic Control of Wafer Processing Paths in Semiconductor Manufacturing Processes			
	09/928,473	08/14/01	Koh	Tool Services Layer for Providing Tool Service Functions in Conjunction with Tool Functions			
	09/928,474	08/14/01	Krishnamurthy et al.	Experiment Management System, Method and Medium			
	09/943,383	08/31/01	Shanmugasundram et al.	In Situ Sensor Based Control of Semiconductor Processing Procedure			
	09/943,955	08/31/01	Shanmugasundram et al.	Feedback Control of a Chemical Mechanical Polishing Device Providing Manipulation of Removal Rate Profiles			
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EXAMINER <i>mae</i>				DATE CONSIDERED 1/21/08			

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EXAMINER'S INITIALS	PATENT APP. NO.	FILING DATE	NAME	TITLE	CLASS	SUB- CLASS	
	10/084,092	02/28/02	Arackaparambil et al.	Computer Integrated Manufacturing Techniques			
	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
	10/135,451	05/01/02	Shanmugasundram et al.	Dynamic Metrology Schemes and Sampling Schemes for Advanced Process Control in Semiconductor Processing			
	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
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FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	61-66104	04/04/86	Japan			X	
	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
	0-397 924 A1	11/22/90	Europe			X	
	2,050,247	08/29/91	Canada			X	
	2,165,847	08/29/91	Canada			X	
	2,194,855	08/29/91	Canada			X	
	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
	8-23166	01/23/96	Japan			X	
	08-50161	02/20/96	Japan			X	
	08-149583	06/07/96	Japan			X	
	08-304023	11/22/96	Japan			X	
	EP 0 747 795 A2	12/11/96	Europe			X	
	09-34535	02/07/97	Japan			X	
	9-246547	09/19/97	Japan			X	
	WO 98/05066	02/05/98	WO			X	
	10-34522	02/10/98	Japan			X	
	10-173029	06/26/98	Japan			X	
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				APPLICANT Joseph Young J. PAIK			
				FILING DATE September 18, 2003		GROUP	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
/	EP 0 869 652 A2	10/07/98	Europe			X	
/	WO 98/45090	10/15/98	WO			X	
/	EP 0 877 308 A2	11/11/98	Europe			X	
/	EP 0 881 040 A2	12/02/98	Europe			X	
/	EP 0 895 145 A1	02/03/99	Europe			X	
/	WO 99/09371	02/25/99	WO			X	
/	11-67853	03/09/99	Japan			X	
/	EP 0 910 123 A1	04/21/99	Europe			X	
/	11-126816	05/11/99	Japan			X	
/	11-135601	05/21/99	Japan			X	
/	WO 99/25520	05/27/99	WO			X	
/	EP 0 932 194 A1	07/28/99	Europe			X	
/	WO 99/59200	11/18/99	WO			X	
/	WO 00/00874	01/06/00	WO			X	
/	WO 00/05759	02/03/00	WO			X	
/	WO 00/35063	06/15/00	WO			X	
/	2000-183001	06/30/00	Japan			X	
/	WO 00/54325	09/14/00	WO			X	
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/	WO 00/79355 A1	12/28/00	WO			X	
/	EP 1 066 925 A2	01/10/01	Europe			X	
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/	EP 1 071 128 A2	01/24/01	Europe			X	
/	WO 01/11679 A1	02/15/01	WO			X	
/	WO 01/15865 A1	03/08/01	WO			X	
/	WO 01/18623 A1	03/15/01	WO			X	
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						Yes	No
	2001-76982	03/23/01	Japan			X	
	WO 01/23865 A1	04/12/01	WO			X	
	EP 1 092 505 A2	04/18/01	Europe			X	
	WO 01/33277 A1	05/10/01	WO			X	
	WO 01/33501 A1	05/10/01	WO			X	
	434103	05/16/01	Taiwan			X	
	436383B	05/28/01	Taiwan			X	
	WO 01/52055 A3	07/19/01	WO			X	
	WO 01/52319 A1	07/19/01	WO			X	
	WO 01/57823 A2	08/09/01	WO			X	
	455938B	09/21/01	Taiwan			X	
	455976	09/21/01	Taiwan			X	
	2001-284299	10/12/01	Japan			X	
	WO 01/80306 A2	10/25/01	WO			X	
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	WO 02/31613 A2	04/18/02	WO			X	
	WO 02/31613 A3	04/18/02	WO			X	
	WO 02/33737 A2	04/25/02	WO			X	
	WO 02/074491 A1	09/26/02	WO			X	
	2002-343754	11/29/02	Japan			X	
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<p align="center">OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</p>		
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